

## 150V N-Ch Power MOSFET

$V_{DS}$		150	V
$R_{DS(on),typ}$	$V_{GS}=10V$	7.5	m
$R_{DS(on),typ}$	$V_{GS}=4.5V$	8.8	m
$I_D$ (Silicon Limited)		87	A
$I_D$ (Package Limited)		60	A

Part Number	Package	Marking
HGN088N15SL	DFN5*6	GN088N15SL

#### Absolute Maximum Ratings at $T_J$

Parameter	Conditions	Value	Unit
Continuous Drain Current (Package Limited)	$T_C$	55	A
	$T_C$	60	
Drain to Source Voltage	$V_{DS}$ -		
Gate to Source Voltage	$V_{GS}$ -	20	
Pulsed Drain Current	$I_{DM}$		
Avalanche Energy, Single Pulse	$E_{AS}$ L=0.4mH, $T_C$		
Operating and Storage Temperature	$T_J, T_{stg}$ -		

#### Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{JA}$	55	
Thermal Resistance Junction-Case	$R_{JC}$	0.9	

## Electrical Characteristics at $T_j$

### Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\text{ A}$	150	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\text{ A}$	1	2	3	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS}=0V, V_{DS}=150V, T_j$	-	-	1	A
		$V_{GS}=0V, V_{DS}=150V, T_j$	-	-	100	
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} \leq 99, V_{DS}=0V$	-	-	100	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	7.5	8.8	m
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=20A$	-	8.8	11	m
Transconductance	$g_{fs}$	$V_{DS}=5V, I_D=20A$	-	85	-	S
Gate Resistance	$R_G$	$V_{GS}=0V, V_{DS}\text{ Open}, f=1\text{MHz}$	-	0.95	-	

### Dynamic Characteristics

Input Capacitance			-	4758	-	pF
Total Gate Charge	$Q_g(10V)$					
Gate to Source Charge	$Q_{gs}$					

Fig 1. Typical Output Characteristics

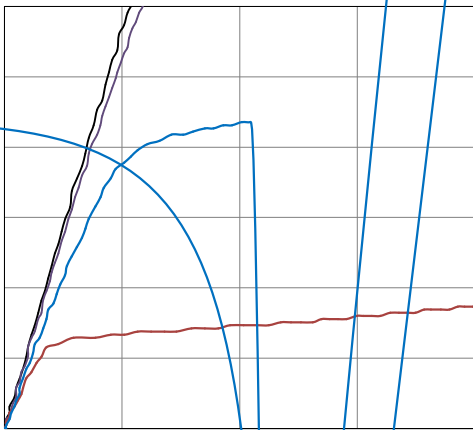


Figure 2. On-Resistance vs. Gate-Source Voltage

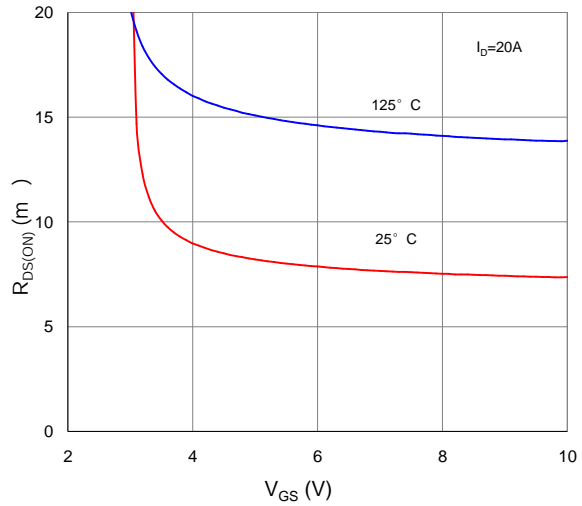


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

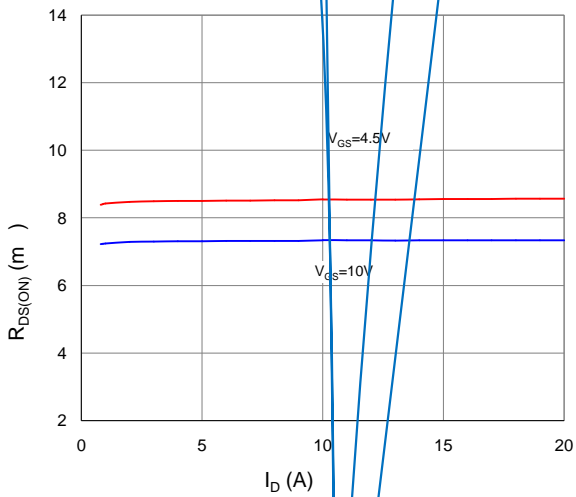


Figure 4. Normalized On-Resistance vs. Junction Temperature

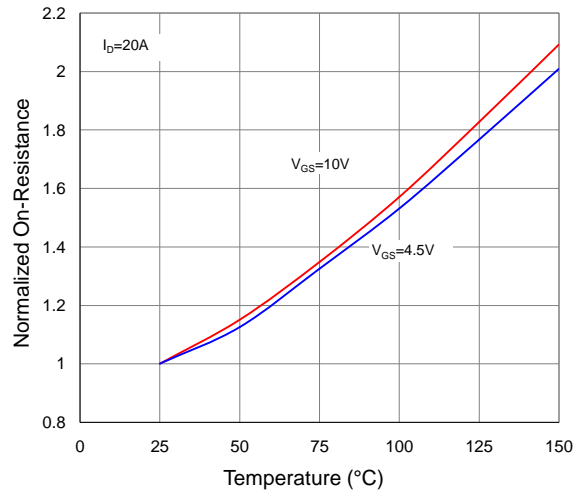


Figure 5. Typical Transfer Characteristics

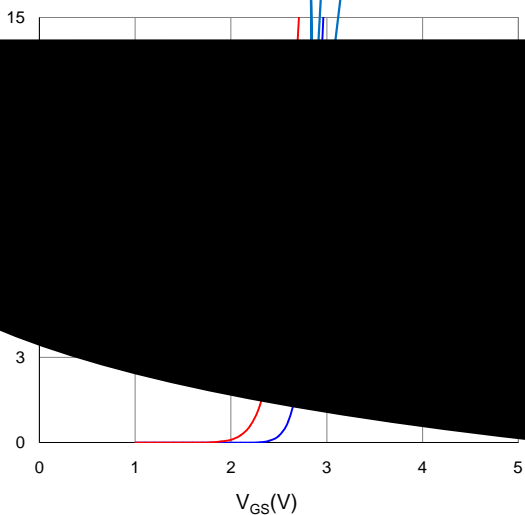


Figure 6. Typical Source-Drain Diode Forward Voltage

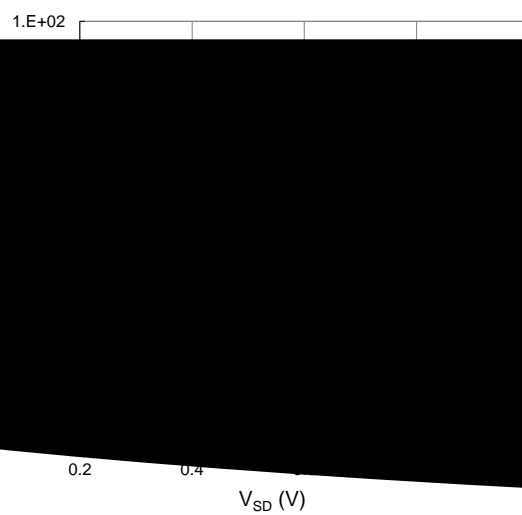


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

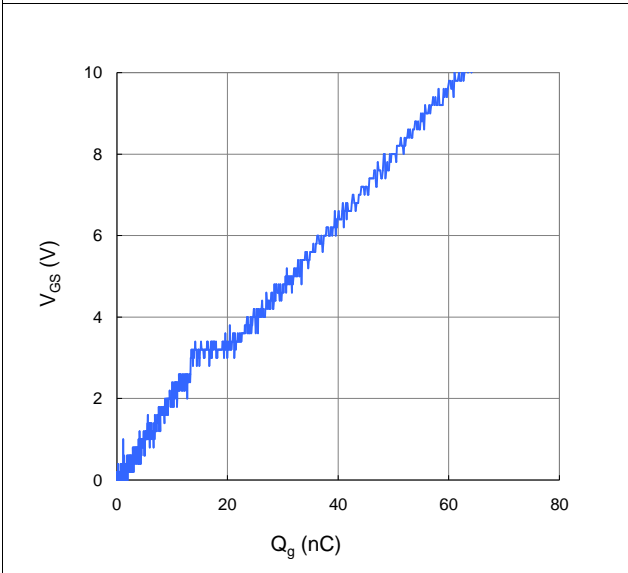


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

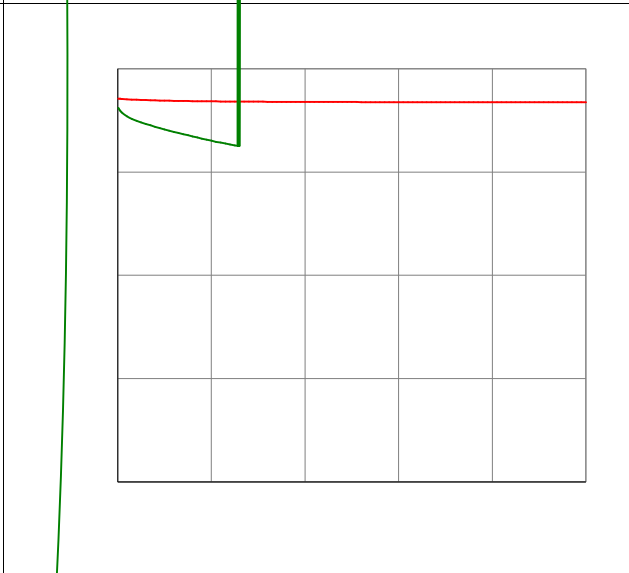


Figure 9. Maximum Safe Operating Area

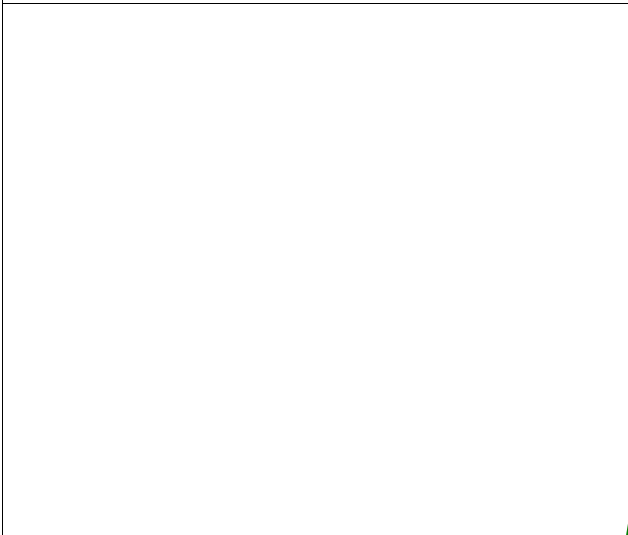


Figure 10. Maximum Drain Current vs. Case Temperature

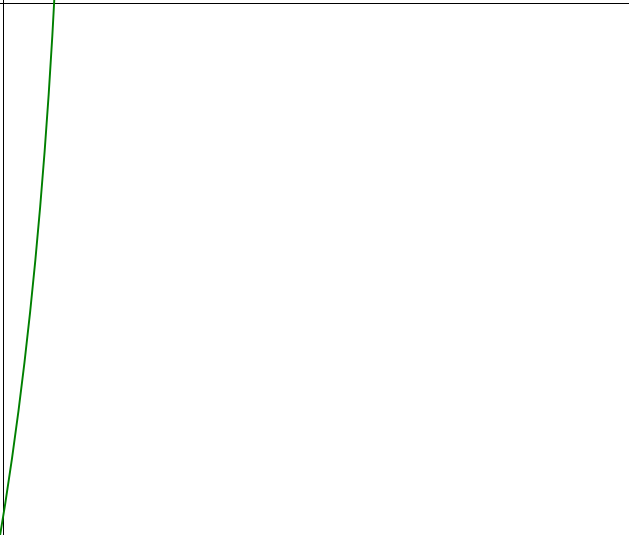
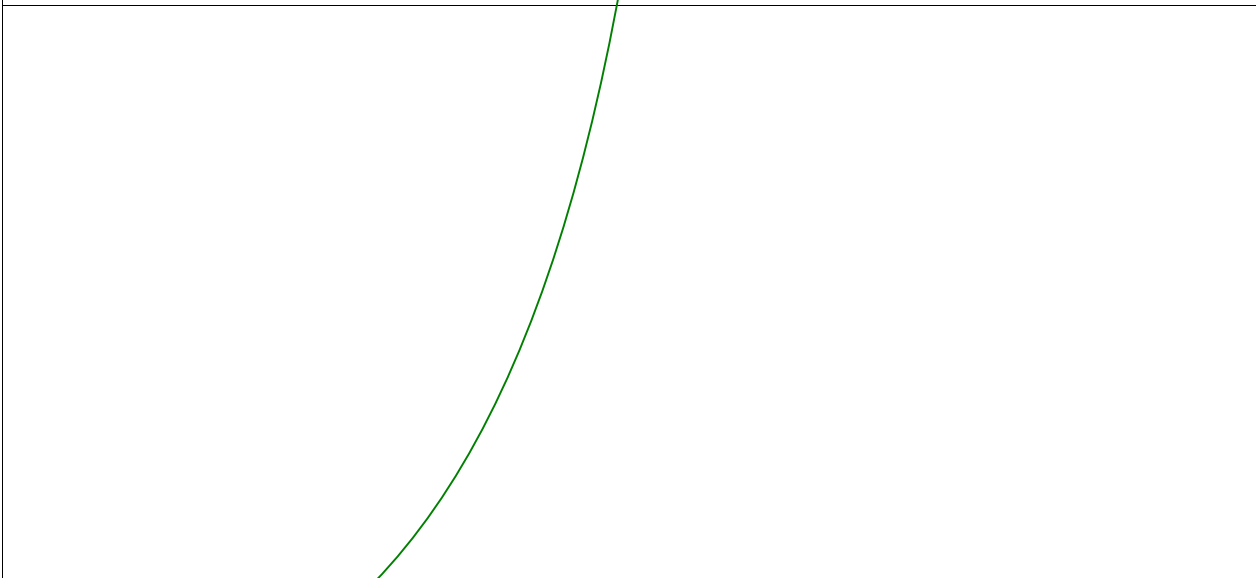
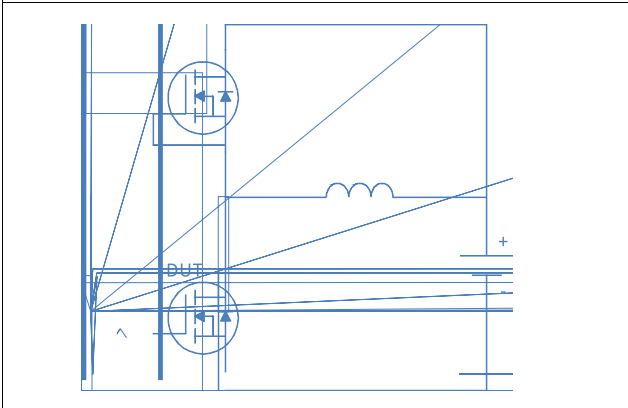


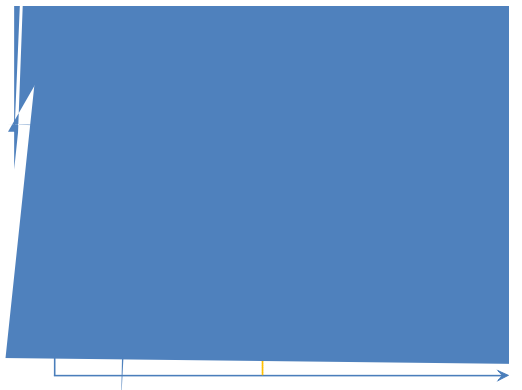
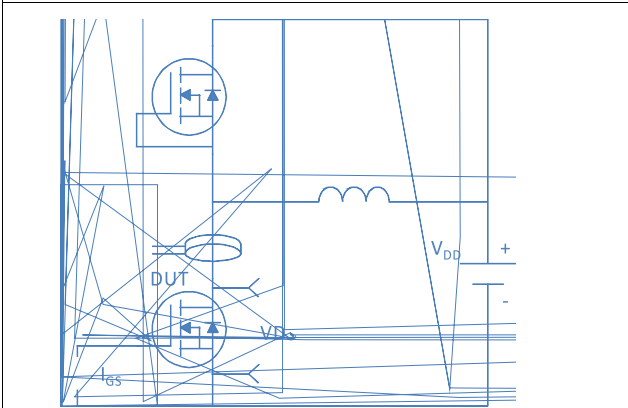
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient



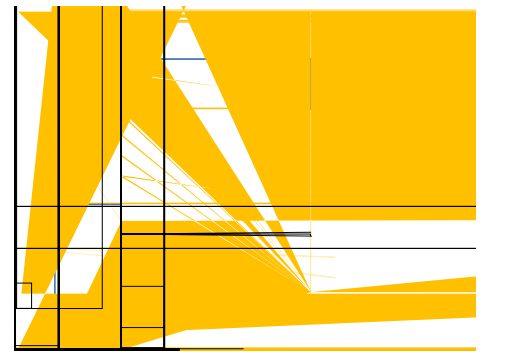
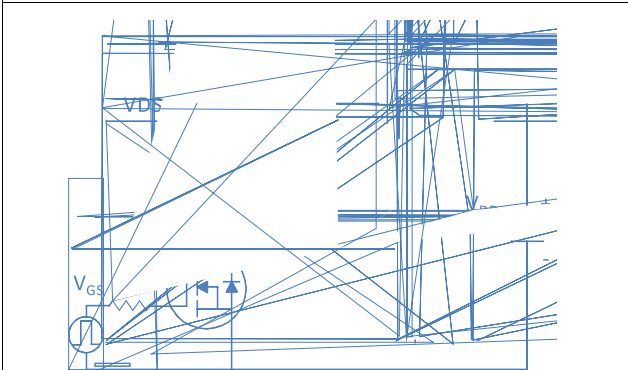
Inductive switching Test



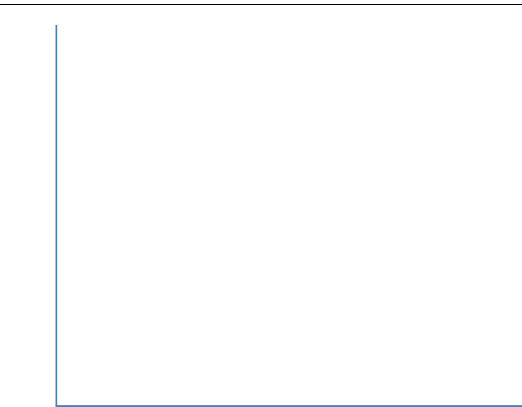
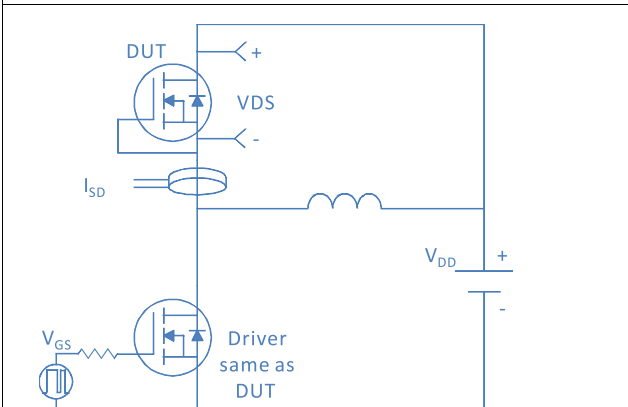
Gate Charge Test



Uclamped Inductive Switching (UIS) Test



Diode Recovery Test



## Package Outline

### DFN5x6\_P, 8 Leads

